

PQFP (PQ100), Heat Sink PQFP (HQ100) Package

TOP VIEW BOTTOM VIEW aaaCA-BD4X D D2 PIN ID 1 D1 \mathbb{D} 100 H (0) Ó А В Ε E1 :0010d E2 ...)X Pe /5 /6\ b-D|4X bbb H A-B J LEAD FINISH: SOLDER PLATE 5°-16° SEE DETAIL 'A' -С 0° MIN. Α 0.20 MIN. Н 5°-16° \subset Α2 0.25 S MILLIMETERS GAGE PLANE Y M B -7* MIN. NDM. MAX. Α1 C А A A 3.40 1.60 REF. A1 0.25 A 0.50 DETAIL 'A 2,50 2,90 Аz 2.70 \mathbb{D} 23.20 BSC 20.00 BSC \mathbb{D}_1 NOTES: 18.85 REF. Dг 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994. Ε 17.20 BSC 2. DIMENSIONS 'D1' AND 'E1' DO NOT INCLUDE MOLD PROTRUSION. 14.00 BSC E1 ALLOWABLE MOLD PROTRUSION IS 0.25mm PER SIDE. Ег 12.35 REF. 3. THE TOP OF PACKAGE MAY BE EQUAL TO OR SMALLER THAN 0.73 0.88 1.03 L THE BOTTOM OF PACKAGE BY 0.15 MILLIMETERS. 0.65 BSC e 4. PACKAGE CONFORMS TO JEDEC OUTLINE MS-022-GC1 b 0.22 A 0.40 /5. THE SAME PACKAGE DIMENSIONS APPLY FOR THERMALLY ENHANCED 0.13 C A 0.23 PRODUCTS. HEAT SINK IS ADDED. THE PACKAGE CODE IS 'HQ'. 0.25 A A aaa ▲ MARK ORIENTATION WITH RESPECT TO PIN−1 I.D. 0.20 A A bbb IF 2 OR MORE CIRCLES EXIST ON TOP OF THE PACKAGE, USE 0.10 CCC A A THE SMALLEST CIRCLE AS PIN-1 I.D. 0.13 ddd ty A

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